

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 1234 | 235/494.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:49 |
| L2 | 364 | 355/43.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:49 |
| L3 | 2879 | 355/53.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:49 |
| L4 | 108 | 430/13.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:49 |
| L5 | 558 | 257/620.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:49 |
| L6 | 4 | ((code\$1 or mark\$1) near10 (inside\$1 or wall\$1) near20 notch\$2) same wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:50 |
| L7 | 223 | (((355/53.ccls. and semiconductor) and wafer) and mark) and identical | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:51 |
| L8 | 6875 | (semiconductor adj wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:51 |
| L9 | 640 | (code\$1 or mark\$1) same first same second same wafer same semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:51 |
| L10 | 1249 | replace same mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:51 |

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| L11 | 129 | (replace same mark) and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:51 |
| L12 | 1 | (replace same mark) and semiconductor same identification | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/24 15:52 |
| S1 | 1207 | 235/494.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:21 |
| S2 | 2666 | 355/53.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:23 |
| S3 | 364 | 355/43.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:23 |
| S4 | 108 | 430/13.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:24 |
| S5 | 530 | 257/620.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:31 |
| S6 | 605 | (code\$1 or mark\$1) same first same second same wafer same semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:31 |
| S7 | 9 | (code\$1 or mark\$1) same first same second same wafer same semiconductor same notch\$2 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:31 |
| S8 | 3 | ((code\$1 or mark\$1) near10 (inside\$1 or wall\$1) near20 notch\$2) same wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:32 |

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|-----|-------|--|---|----|-----|------------------|
| S9 | 2 | "20040129940" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:34 |
| S10 | 2 | "5147824".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:35 |
| S11 | 2 | "20030015806" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 15:41 |
| S12 | 0 | "20030015806".URPN. | USPAT | OR | OFF | 2004/08/06 15:35 |
| S13 | 6 | "4418467".pn. "5028200".pn. "6120607".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 16:10 |
| S14 | 10 | (("4547446") or ("4327292") or ("6120607") or ("4701050") or ("6277658") or ("6268641") or ("6004405") or ("5907144") or ("5876819") or ("4418467")).PN. | USPAT; USOCR | OR | OFF | 2004/08/06 16:12 |
| S15 | 10 | (("4547446") or ("4327292") or ("6120607") or ("4701050") or ("6277658") or ("6268641") or ("6004405") or ("5907144") or ("5876819") or ("4418467")).PN. | USPAT; USOCR | OR | OFF | 2004/08/06 16:29 |
| S16 | 17105 | chiba.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 16:29 |
| S17 | 942 | S16 and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 16:29 |
| S18 | 22 | S17 and notch | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 16:29 |
| S19 | 7 | S18 and marking | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 17:50 |

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| S20 | 4 | "6268641".pn. "6312876".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/08/06 17:50 |
| S21 | 0 | 235/494.ccls. and chiba.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 17:56 |
| S22 | 0 | jp-223380-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 17:56 |
| S23 | 9 | "223380" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 17:57 |
| S24 | 0 | jp-223380-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 17:58 |
| S25 | 0 | jp-5923512-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 17:58 |
| S26 | 2 | jp-2000223380-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:00 |
| S27 | 0 | jp-2175154-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:00 |
| S28 | 1 | jp-3116919-\$.did. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:00 |
| S29 | 15423 | chiba.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:02 |

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|-----|-------|---|---|----|-----|------------------|
| S30 | 818 | chiba.in. and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:02 |
| S31 | 58 | (chiba.in. and semiconductor) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:05 |
| S32 | 153 | (chiba.in. and semiconductor) and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:06 |
| S33 | 83 | 235/494.ccls. and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:10 |
| S34 | 8 | (235/494.ccls. and semiconductor) and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:06 |
| S35 | 34 | (235/494.ccls. and semiconductor) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:47 |
| S36 | 2 | "6305677".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:16 |
| S37 | 174 | 269/13.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:18 |
| S38 | 81423 | semiconductor adj2 wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:19 |
| S39 | 4744 | (semiconductor adj2 wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:19 |

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|-----|------|--|---|----|-----|------------------|
| S40 | 4500 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:20 |
| S41 | 61 | (((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:53 |
| S42 | 22 | semiconductor adj mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:52 |
| S43 | 1154 | 355/53.ccls. and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:29 |
| S44 | 1052 | (355/53.ccls. and semiconductor) and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:29 |
| S45 | 415 | ((355/53.ccls. and semiconductor) and wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:30 |
| S46 | 8 | (((355/53.ccls. and semiconductor) and wafer) and mark) and reproduce | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:32 |
| S47 | 0 | (((355/53.ccls. and semiconductor) and wafer) and mark) and efface | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:32 |
| S48 | 5 | (((355/53.ccls. and semiconductor) and wafer) and mark) and erase | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:34 |
| S49 | 0 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce adj erased adj marks) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:35 |

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|-----|-----|--|---|----|-----|------------------|
| S50 | 0 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks)) and efface | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:35 |
| S51 | 10 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks)) and notch | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:35 |
| S52 | 300 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce erased marks) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:38 |
| S53 | 0 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce near erased near marks) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:39 |
| S54 | 0 | (((355/53.ccls. and semiconductor) and wafer) and mark) and (reproduce same erased same marks) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:39 |
| S55 | 121 | (((355/53.ccls. and semiconductor) and wafer) and mark) and identical | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:40 |
| S56 | 9 | (((355/53.ccls. and semiconductor) and wafer) and mark) and identical) and reproduce\$2 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:44 |
| S57 | 172 | (((355/53.ccls. and semiconductor) and wafer) and mark) and prevent | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:44 |
| S58 | 3 | (((355/53.ccls. and semiconductor) and wafer) and mark) and prevent) and erase | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:53 |
| S59 | 354 | 355/43.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:53 |

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|-----|-------|---|---|----|-----|------------------|
| S60 | 84 | 355/43.ccls. and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:53 |
| S61 | 71 | (355/43.ccls. and semiconductor) and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:53 |
| S62 | 1 | ((355/43.ccls. and semiconductor) and wafer) and mark) and erase | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:54 |
| S63 | 45 | ((355/43.ccls. and semiconductor) and wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:58 |
| S64 | 25968 | "355"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:58 |
| S65 | 2116 | "355"/\$.ccls. and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:59 |
| S66 | 1469 | ("355"/\$.ccls. and semiconductor) and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:59 |
| S67 | 497 | ("355"/\$.ccls. and semiconductor) and wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:59 |
| S68 | 8 | ((("355"/\$.ccls. and semiconductor) and wafer) and mark) and erase | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 18:59 |
| S69 | 13 | ((("355"/\$.ccls. and semiconductor) and wafer) and mark) and reproduce | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 19:02 |

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|-----|----|--|---|----|-----|------------------|
| S70 | 1 | ((("355"/\$.ccls. and semiconductor) and wafer) and mark) and erase) and (((("355"/\$.ccls. and semiconductor) and wafer) and mark) and reproduce) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2002/05/30 19:02 |
| S71 | 6 | (235/494.ccls. and semiconductor) and mark and duplicate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:51 |
| S72 | 0 | (235/494.ccls. and semiconductor) and (duplicate adj mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:51 |
| S73 | 3 | (235/494.ccls. and semiconductor) and (duplicate same mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:51 |
| S74 | 0 | (semiconductor adj mark) same duplicate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:53 |
| S75 | 0 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate same mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:53 |
| S76 | 0 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate near mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:53 |
| S77 | 0 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and (duplicate adj mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:53 |
| S78 | 72 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:54 |
| S79 | 3 | ((semiconductor adj2 wafer) and mark) and (semiconductor adj wafer)) and reproduce) and duplicate | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/09 18:54 |

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|-----|-------|---|---|----|-----|------------------|
| S80 | 26645 | "355"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/10 12:08 |
| S81 | 102 | 430/13.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/10 12:09 |
| S82 | 435 | 257/620.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/01/10 12:09 |
| S83 | 1104 | 235/494.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:08 |
| S84 | 27013 | "355"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:08 |
| S85 | 462 | 257/620.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:09 |
| S86 | 104 | 430/13.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:09 |
| S87 | 1015 | replace same mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:09 |
| S88 | 99 | (replace same mark) and semiconductor | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:12 |
| S89 | 3 | ((replace same mark) and semiconductor) and "235"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:14 |

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|-----|-------|---|---|----|-----|------------------|
| S90 | 89611 | semiconductor adj wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:19 |
| S91 | 5456 | (semiconductor adj wafer) and mark | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:20 |
| S92 | 2 | ((semiconductor adj wafer) and mark) and (replace near10 mark) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2003/05/30 12:20 |